



DUAL N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

BV _{DSS}	R _{DS(ON)} Max	I _D T _A = +25°C
20V	$5.4 m\Omega$ @ $V_{GS} = 4.5 V$	14.5A
	$6.2 m\Omega @ V_{GS} = 4.0 V$	13.5A
	$6.4 \text{m}\Omega @ V_{GS} = 3.7 \text{V}$	13.0A
	$7.5 \text{m}\Omega @ V_{GS} = 3.1 \text{V}$	12.0A
	$9.6 \text{m}\Omega @ V_{GS} = 2.5 \text{V}$	10.5A

Features

- Low On-Resistance
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- ESD Protected Gate
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description

This new generation MOSFET is designed to minimize the on-state resistance (R_{DS(ON)}), yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

- Power Management Functions
- Battery Pack
- Load Switch

Mechanical Data

- Case: U-DFN2030-6 (Type B)
- Case Material: Molded Plastic, "Green" Molding Compound.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: NiPdAu over Copper Leadframe.
 Solderable per MIL-STD-202, Method 208
- Terminal Connections: See Diagram Below
- Weight: 0.012 grams (Approximate)



ESD PROTECTED

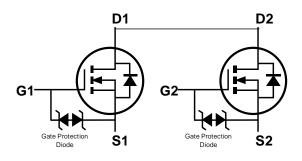
U-DFN2030-6 (Type B)



Bottom View



Top View Pin-Out



Equivalent Circuit

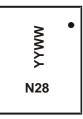
Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2008LFU-7	U-DFN2030-6 (Type B)	3,000/Tape & Reel
DMN2008LFU-13	U-DFN2030-6 (Type B)	10,000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



N28 = Product Type Marking Code YYWW = Date Code Marking YY = Last Two Digits of Year (ex: 16 for 2016) WW = Week Code (01 to 53)



Maximum Ratings ($@T_A = +25^{\circ}C$, unless otherwise specified.)

Characteristic			Symbol	Value	Unit
Drain-Source Voltage			V _{DSS}	20	V
Gate-Source Voltage			V_{GSS}	±12	V
Continuous Drain Current (Note 6) V _{GS} = 4.5V	I _D	14.5 11.5	А		
Maximum Continuous Body Diode Forward Current (Note 6)			Is	2.2	Α
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)			I _{DM}	75	Α
Avalanche Current (Note 7) L = 0.1mH			I _{AS}	10	Α
Avalanche Energy (Note 7) L = 0.1mH			E _{AS}	20	mJ

Thermal Characteristics

Characteristic	Symbol	Value	Unit	
Total Power Dissipation (Note 5)	$T_A = +25^{\circ}C$	P_{D}	1.0	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady State	R⊝JA	123	°C/W
Total Power Dissipation (Note 6)	$T_A = +25^{\circ}C$	P_{D}	1.7	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady State	R⊝JA	73	°C/W
Thermal Resistance, Junction to Case	Rejc	12	C/VV	
Operating and Storage Temperature Range		$T_{J_1}T_{STG}$	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

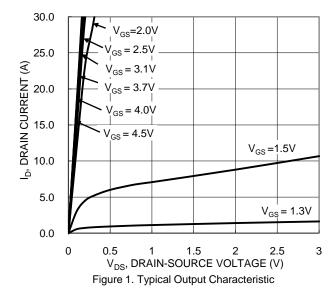
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 8)							
Drain-Source Breakdown Voltage	BV _{DSS}	20	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current T _J = +25°C	I _{DSS}	I	_	1.0	μA	$V_{DS} = 16V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	l	_	±10	μΑ	$V_{GS} = \pm 9.6V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 8)							
Gate Threshold Voltage	V _{GS(TH)}	0.5	_	1.5	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
			4.7	5.4		$V_{GS} = 4.5V, I_D = 5.5A$	
			4.8	6.2		$V_{GS} = 4.0V, I_D = 5.5A$	
Static Drain-Source On-Resistance	R _{DS(ON)}	_	4.9	6.4	mΩ	$V_{GS} = 3.7V, I_D = 5.5A$	
			5.1	7.5		$V_{GS} = 3.1V, I_D = 5.5A$	
			5.7	9.6		$V_{GS} = 2.5V, I_D = 5.5A$	
Diode Forward Voltage	V_{SD}		0.7	1.2	V	$V_{GS} = 0V, I_{S} = 11A$	
DYNAMIC CHARACTERISTICS (Note 9)							
Input Capacitance	CISS	1	1,418	_	pF	101/1/	
Output Capacitance	Coss	-	323	_	pF	$V_{DS} = 10V, V_{GS} = 0V,$ f = 1.0MHz	
Reverse Transfer Capacitance	C _{RSS}	1	106	_	pF	1 = 1.000112	
Gate Resistance	R_g	1	465	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Q_g	1	18.7	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	I	42.3	_	nC	V _{DS} = 16V. I _D = 11A.	
Gate-Source Charge	Q_{gs}	-	3.2	_	nC	VDS = 16V, ID = 11A,	
Gate-Drain Charge	Q_{gd}	_	4.4	_	nC	1	
Turn-On Delay Time	t _{D(ON)}	_	277	_	ns		
Turn-On Rise Time	t _R	_	653	_	ns	$V_{DD} = 16V, I_D = 5.5A,$	
Turn-Off Delay Time	t _{D(OFF)}	_	1,989	_	ns	$V_{GS} = 4.5V$, $R_g = 6\Omega$	
Turn-Off Fall Time	t _F	_	1,208	_	ns	1	
Reverse Recovery Time	t _{RR}		492	_	ns	1 44 4 31/34 4004/	
Reverse Recovery Charge	Q _{RR}		908	_	nC	I _F =11 A, di/dt = 100A/μs	

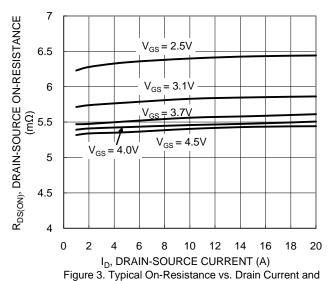
Notes:

- 5. Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.
- 6. Device mounted on FR-4 substrate PC board, 2oz copper, with 1-inch square copper plate.
- 7. IAS and EAS ratings are based on low frequency and duty cycles to keep $T_J = +25^{\circ}C$. 8. Short duration pulse test used to minimize self-heating effect.
- 9. Guaranteed by design. Not subject to product testing.

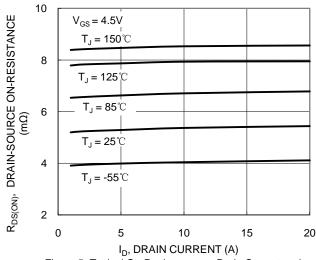


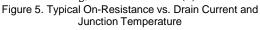






Gate Voltage





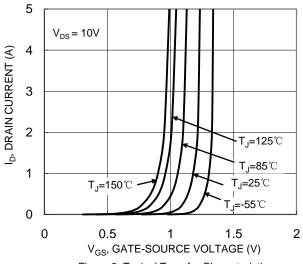
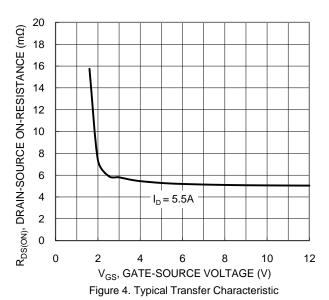


Figure 2. Typical Transfer Characteristic



2 V_{GS} = 4.5V, I_D = 5.5A V_{GS} = 2.5V, I_D = 2.5V, I

Temperature





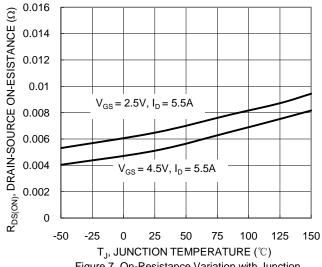
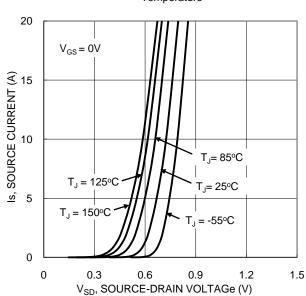
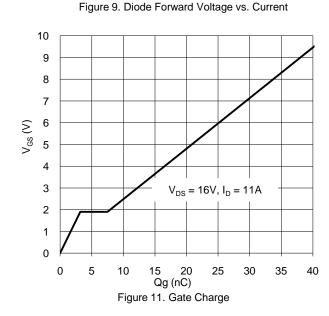


Figure 7. On-Resistance Variation with Junction Temperature





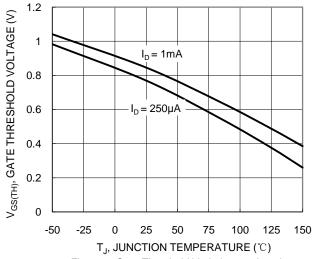
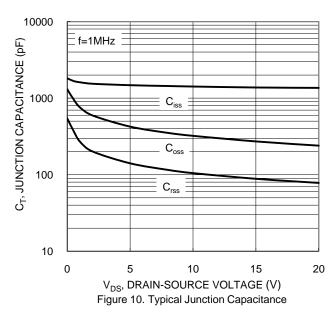
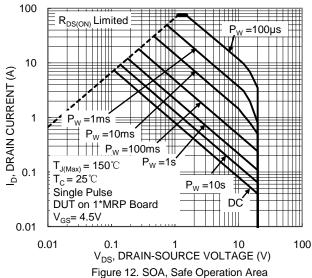


Figure 8. Gate Threshold Variation vs. Junction Temperature







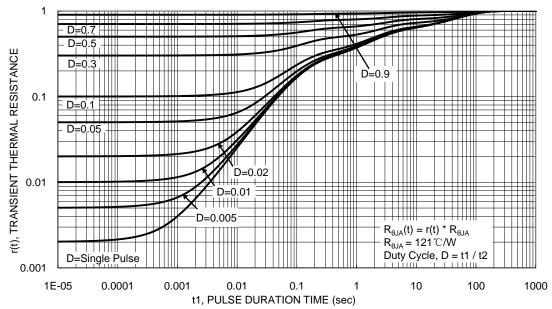


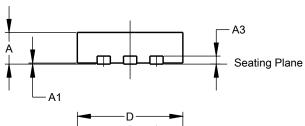
Figure 13. Transient Thermal Resistance

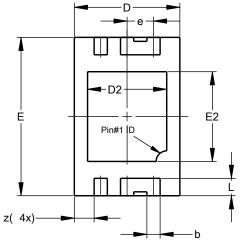


Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2030-6 (Type B)



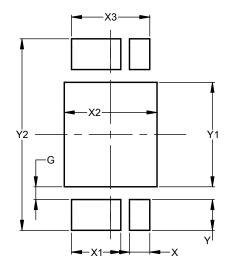


U-DFN2030-6 (Type B)					
Dim	Min	Max	Тур		
Α	0.55	0.65	0.60		
A 1	0.00	0.05	0.02		
A3	-	-	0.15		
b	0.20	0.30	0.25		
D	1.95	2.05	2.00		
D2	1.40	1.60	1.50		
Е	2.95	3.05	3.00		
E2	1.65	1.75	1.70		
е	-	-	0.50		
L	0.28	0.38	0.33		
Z	-	-	0.375		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

U-DFN2030-6 (Type B)



Dimensions	Value		
Dillielisions	(in mm)		
G	0.220		
Х	0.350		
X1	0.850		
X2	1.600		
Х3	1.350		
Y	0.530		
Y1	1.800		
Y2	3.300		



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